

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WEI-CHENG WU	05/15/2020
CHIEN-CHIA CHIU	05/15/2020
CHENG-HSIEN HSIEH	05/15/2020
LI-HAN HSU	05/19/2020
MENG-TSAN LEE	05/15/2020
TSUNG-SHU LIN	05/19/2020
RECEIVING PARTY DATA	
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City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16893440
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	06/08/2020
Total Attachments: 4	

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

☒ Declaration Submitted With Initial Filing

OR

☐ Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

**SEMICONDUCTOR PACKAGE AND MANUFACTURING METHOD
THEREOF**

As a below named inventor (hereinafter designated as the undersigned), I hereby
declare that:

This declaration is directed to:

☒ The attached application,

OR

☐ United States Application Number or PCT International application number

_____ Filed on _____

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in
the application.

The undersigned hereby acknowledge that any willful false statement made in this
declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more
than five (5) years, or both.

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DECLARATION AND ASSIGNMENT FOR UTILITY OR DESIGN PATENT APPLICATION

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS, 1. Taiwan Semiconductor Manufacturing Co., Ltd.
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Wei-Cheng Wu Date: 2020/5/15

Legal Name of Sole or First Inventor: **Wei-Cheng Wu**

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Chien-Chia Chiu Date: 2020/5/15

Legal Name of Additional Joint Inventor, if any: **Chien-Chia Chiu**

Residence: Taoyuan City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Cheng-Hsien Hsieh Date: 2020/5/15

Legal Name of Additional Joint Inventor, if any: **Cheng-Hsien Hsieh**

Residence: Kaohsiung City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Li-Han Hsu Date: 2020/5/19

Legal Name of Additional Joint Inventor, if any: **Li-Han Hsu**

Residence: Hsin-Chu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Meng-Tsan Lee Date: 2020/5/15

Legal Name of Additional Joint Inventor, if any: **Meng-Tsan Lee**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Tsung-Shu Lin Date: 2020/5/19

Legal Name of Additional Joint Inventor, if any: **Tsung-Shu Lin**

Residence: New Taipei City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.